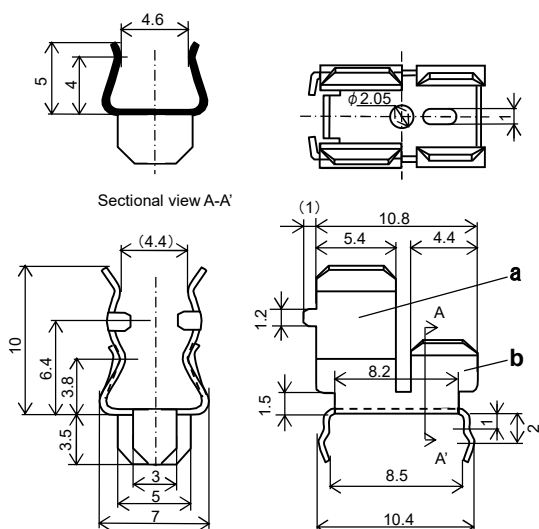




RoHS



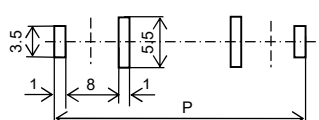
**Dimensions and construction:**



Materials: C5191R-1/2H, 0.4 mm thick  
 Surface treatments: Tin plating

Dimensional tolerances where not noted	
Dimensional range (mm)	Tolerance ( $\pm$ mm)
$L \leq 3$	0.35
$3 < L \leq 6$	0.45
$6 < L \leq 18$	0.55
$18 < L \leq 30$	0.7
$30 < L \leq 50$	0.9
$50 < L \leq 80$	1.0
$80 < L \leq 120$	1.2

**Mounting holes:**



(mm)

For  $\phi 5.2 \times 20$  mm: P=30.6  
 For  $\phi 6.35 \times 30$  mm: P=29.8  
 For  $\phi 6.35 \times 31.8$  mm: P=31.6

**Characteristics:**

- Fuse size:  $\phi 5.2 \times 20$  mm,  $\phi 6.35 \times 30$  mm or  $\phi 6.35 \times 31.8$  mm
- Rated current: AC/DC 15 A
- Insertion/Withdrawal force: 5 N–25 N measured using a steel dummy fuse of  $\phi 6.35$  mm for the side **a** and  $\phi 5.2 \times 20$  mm for the side **b**.
- Contact resistance: 2 m $\Omega$  or less when measured by a fall-of-potential method at 100 mA/DC 60 V or by a low ohmmeter, using a copper dummy fuse of  $\phi 6.35$  mm for the side **a** and  $\phi 5.2 \times 20$  mm for the side **b**.
- Solderability: This fuse clip shall satisfy all the requirements specified in JIS C 60068-2-20 when tested as per [the soldering test Ta] Method 1 of the same standard.

## Resistance to soldering heat:

### Wave soldering:

The soldering conditions stated below may be influenced by the material/shape and dimensions of the board, size of the copper foil, and/or heat capacity of the respective components on the board, besides such factors as temperature/duration of preheating, material of solder, temperature of the solder bath, and/or the duration of dipping.

- \* Temperature of molten solder: 260±5 °C
- \* Duration: 10±0.5 s

### Hand soldering with soldering iron:

Depending on the components to which the fuse clip is attached (e.g., copper foil on the board) and/or heat capacity of the soldering iron tip, the soldering conditions may vary from those specified below.

- \* Soldering iron tip temperature: 360±10 °C
- \* Duration: 3±0.5 s

Specifications described above are examples when facilities in our company are used. Please make sufficient evaluations under the actual conditions in your company because the conditions may vary depending on facilities, solder type, solder quantity, board size, and board material.

## Usage conditions:

- \* Ambient temperature: -40 °C—+85 °C
- \* Ambient humidity: 85% RH or less

## Storage conditions and storage period:

Products packaged as delivered can be stored for one year from our shipment under the following conditions.

- \* Ambient temperature: -30 °C—+40 °C (no condensation)
- \* Ambient humidity: 85% RH or less
- \* Ambient atmosphere: Not exposed to corrosive gas or sea breeze  
No visible dust  
Not exposed to direct sunlight
- \* Load: No application of load that may cause deformation or degradation of the product.

## Environmental information:

This product conforms to the EU RoHS Directive 2011/65/EU. The six hazardous substances (lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls [PBB], and polybrominated diphenyl ethers [PBDE]) specified in the EU RoHS Directive are not used intentionally in this product. However, when lead is used in applications exempted from the requirements of the Directive, this will be indicated in the Dimensions and Construction section of the corresponding product specification.

**Packaging:**

- 1,000 fuse clips are packed into a colorless transparent polyethylene bag.
- An identification label is attached to each bag.
- The following are indicated on the identification label:
  - \* Product name
  - \* Quantity
  - \* Date

**Ordering specifications:**

SOC product name: H-0048-2

**Contact information:**

SOC is a global ISO-9001 and TS16949 registered company headquartered in Japan with subsidiaries in Asia, Europe, and North America.

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